

SNx4HC151 8 线路到 1 线路数据选择器/多路复用器

1 特性

- 2V 至 6V 的宽工作电压范围
- 输出可驱动多达 10 个 LSTTL 负载
- 低功耗， I_{CC} 最大值为 80 μA
- t_{pd} 典型值 = 13ns
- 电压为 5V 时，输出驱动为 $\pm 6mA$
- 低输出电流，最大值 1 μA
- 8 线至 1 线多路复用器可作为以下器件运行：
 - 布尔函数发生器
 - 并行转串行转换器
 - 数据选择器

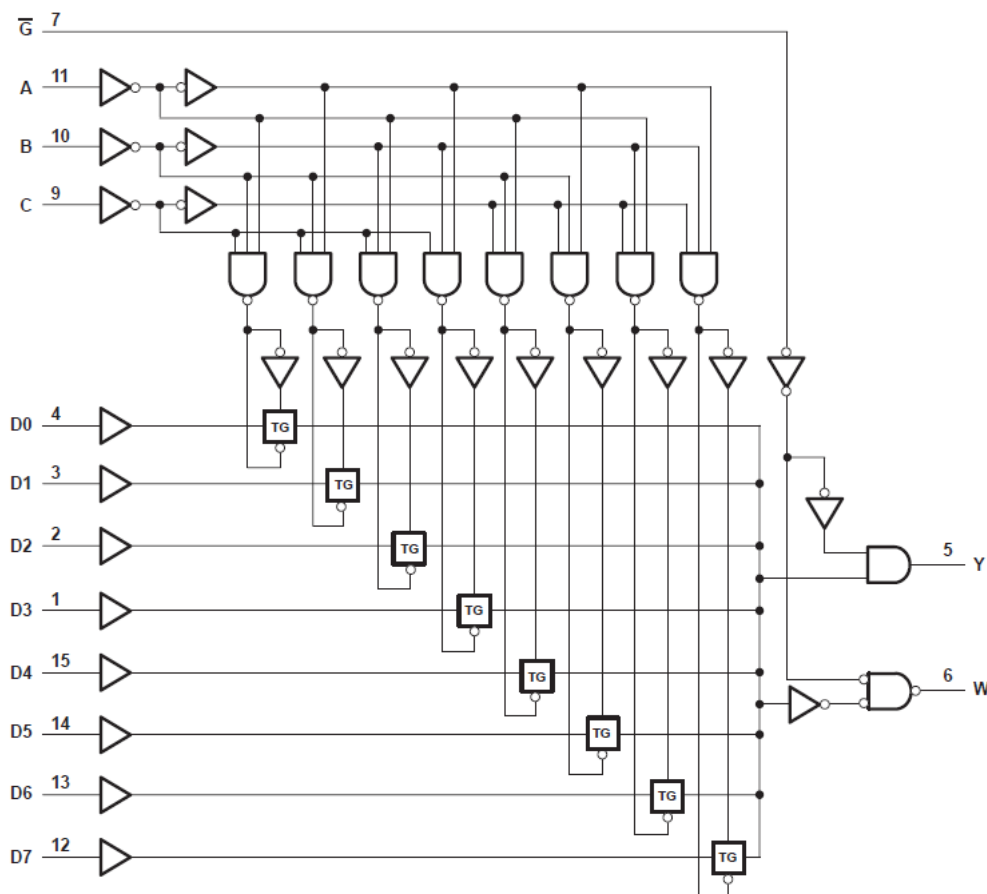
2 说明

该数据选择器/多路复用器支持完整二进制解码，可从八个数据源中选择其中一个。选通 ($\overline{G}$) 输入必须设为逻辑低电平，才能启用输入。将选通端子设为高电平，会强制标准输出端 (Y) 输出低电平，反相输出端 (W) 输出高电平。

器件信息

器件型号	封装 ⁽¹⁾	封装尺寸 (标称值)
SN54HC151J	CDIP (16)	24.38mm × 6.92mm
SN74HC151D	SOIC (16)	9.90mm × 3.90mm
SN74HC151N	PDIP (16)	19.31mm × 6.35mm
SN74HC151NS	SO (16)	6.20mm × 5.30mm
SN74HC151PW	TSSOP (16)	5.00mm × 4.40mm
SNJ54HC151FK	LCCC (20)	8.89mm × 8.45mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。



所示引脚编号用于 D、J、N、NS、PW 和 W 封装。

功能方框图



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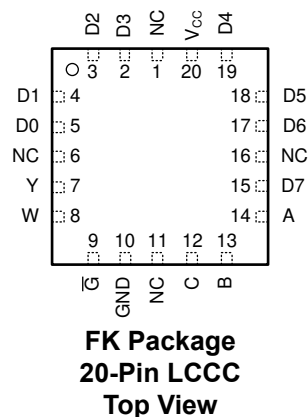
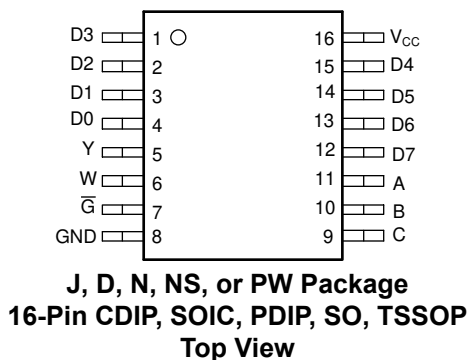
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3 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision E (September 2003) to Revision F (February 2022)	Page
• 更新了整个文档中的编号、格式、表格、图和交叉参考，以反映现代数据表标准.....	1

4 Pin Configuration and Functions



5 Specifications

5.1 Absolute Maximum Ratings

over operating free-air temperature range (unless otherwise noted)⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage range		- 0.5	7	mA
I _{IK}	Input clamp current ⁽²⁾	V _I < 0 or V _I > V _{CC}		±20	mA
I _{OK}	Output clamp current ⁽²⁾	V _O < 0 or V _O > V _{CC}		±20	mA
I _O	Continuous output current	V _O = 0 to V _{CC}		±35	mA
	Continuous current through V _{CC} or GND			±70	mA
T _J	Junction temperature			150	°C
T _{stg}	Storage temperature		- 65	150	°C

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under [§ 5.2](#) is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

5.2 Recommended Operating Conditions⁽¹⁾

			SN54HC151			SN74HC151			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V _{CC}	Supply voltage		2	5	6	2	5	6	V
V _{IH}	High-level input voltage	V _{CC} = 2 V	1.5			1.5			V
		V _{CC} = 4.5 V	3.15			3.15			
		V _{CC} = 6 V	4.2			4.2			
V _{IL}	Low-level input voltage	V _{CC} = 2 V			0.5			0.5	V
		V _{CC} = 4.5 V			1.35			1.35	
		V _{CC} = 6 V			1.8			1.8	
V _I	Input voltage		0		V _{CC}	0		V _{CC}	V
V _O	Output voltage		0		V _{CC}	0		V _{CC}	V
t _i	Input transition rise/fall time	V _{CC} = 2 V			1000			1000	ns
		V _{CC} = 4.5 V			500			500	
		V _{CC} = 6 V			400			400	
T _A	Operating free-air temperature		-55		125	-40		85	°C

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number [SCBA004](#).

5.3 Thermal Information

		D (SOIC)	N (PDIP)	NS (SO)	PW (TSSOP)	UNIT
THERMAL METRIC		16 PINS	16 PINS	16 PINS	16 PINS	
R _{θJA}	Junction-to-ambient thermal resistance ⁽¹⁾	73	67	64	108	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC package thermal metrics](#) application report.

5.4 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS ⁽¹⁾	V _{CC} (V)	T _A = 25°C			SN54HC151		SN74HC151		UNIT
			MIN	TYP	MAX	MIN	MAX	MIN	MAX	
V _{OH}	I _{OH} = -20 mA	2	1.9	1.998		1.9		1.9		V
		4.5	4.4	4.499		4.4		4.4		
		6	5.9	5.999		5.9		5.9		
	I _{OH} = -6 mA	4.5	3.98	4.3		3.7		3.84		
	I _{OH} = -7.8 mA	6	5.48	5.8		5.2		5.34		
V _{OL}	I _{OL} = 20 μA	2		0.002	0.1		0.1		0.1	V
		4.5		0.001	0.1		0.1		0.1	
		6		0.001	0.1		0.1		0.1	
	I _{OL} = 6 mA	4.5		0.17	0.26		0.4		0.33	
	I _{OL} = 7.8 mA	6		0.15	0.26		0.4		0.33	
I _I	V _I = V _{CC} or 0	6		±0.1	±100		±1000		±1000	nA
I _{CC}	I _O = 0	6			8		160		80	μA
C _i		2 to 6		3	10		10		10	pF

(1) V_I = V_{IH} or V_{IL}

5.5 Switching Characteristics

over recommended operating free-air temperature range, C_L = 50 pF (unless otherwise noted) (see [Parameter Measurement Information](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} (V)	T _A = 25°C			SN54HC151		SN74HC151		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A, B, or C	Y or W	2		94	250		360		312	ns
			4.5		30	50		73		63	
			6		25	43		62		54	
	Any D	Y or W	2		74	195		283		244	
			4.5		23	39		57		49	
			6		20	33		48		41	
	$\overline{G}$	Y or W	2		49	127		185		159	
			4.5		15	25		37		32	
			6		13	22		32		28	
t _t		Y or W	2		22	75		110		95	ns
			4.5		9	15		22		19	
			6		8	13		19		16	

5.6 Switching Characteristics

over recommended operating free-air temperature range, $C_L = 150$ pF (unless otherwise noted) (see [Parameter Measurement Information](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} (V)	$T_A = 25^\circ\text{C}$			SN54HC151		SN74HC151		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t_{pd}	A, B, or C	Y or W	2		107	350		525		440	ns
			4.5		33	70		105		88	
			6		30	59		89		76	
	Any D	Y or W	2		90	275		415		345	
			4.5		29	51		83		69	
			6		25	47		72		59	
	$\bar{G}$	Y or W	2		67	205		310		255	
			4.5		21	41		62		51	
			6		18	35		53		43	
t_t		Y or W	2		51	210		315		265	ns
			4.5		16	42		63		53	
			6		14	36		53		45	

5.7 Operating Characteristics

$T_A = 25^\circ\text{C}$

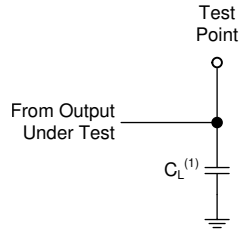
PARAMETER		TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance	No load	70	pF

6 Parameter Measurement Information

Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1 \text{ MHz}$, $Z_O = 50 \Omega$, $t_f < 6 \text{ ns}$.

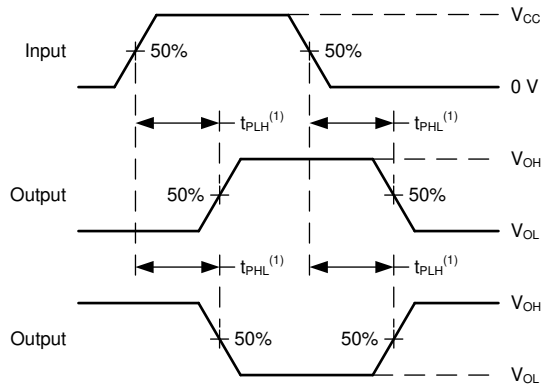
For clock inputs, $f_{\max}$ is measured when the input duty cycle is 50%.

The outputs are measured one at a time with one input transition per measurement.



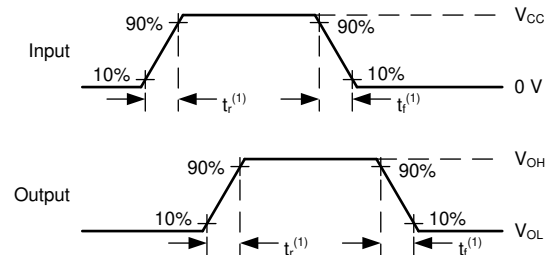
(1) C_L includes probe and test-fixture capacitance.

图 6-1. Load Circuit for Push-Pull Outputs



(1) The greater between t_{PLH} and t_{PHL} is the same as t_{pd} .

图 6-2. Voltage Waveforms, Propagation Delays for Standard CMOS Inputs



(1) The greater between t_r and t_f is the same as t_t .

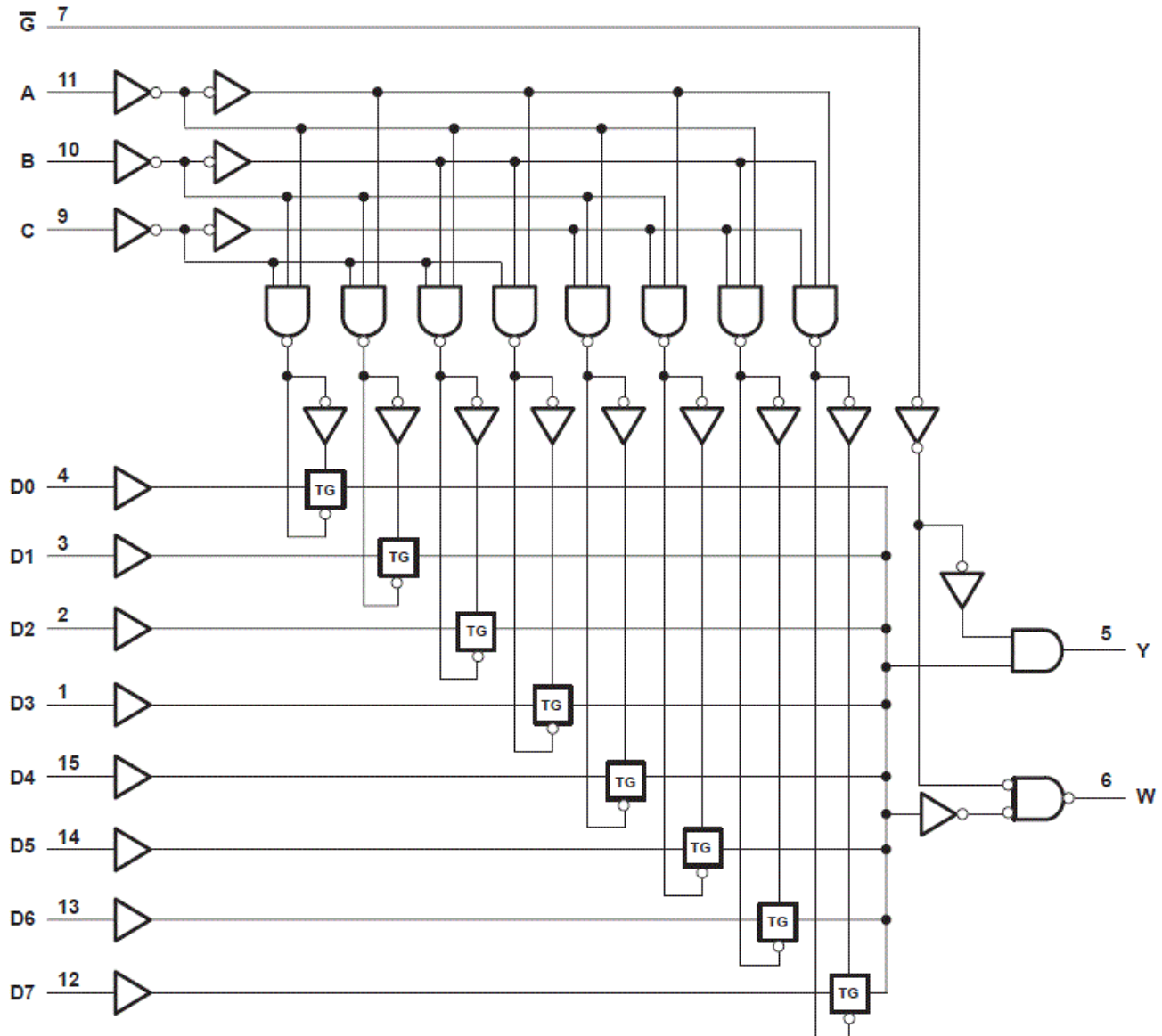
图 6-3. Voltage Waveforms, Input and Output Transition Times for Standard CMOS Inputs

7 Detailed Description

7.1 Overview

This data selector/multiplexer provides full binary decoding to select one of eight data sources. The strobe ($\overline{G}$) input must be at a low logic level to enable the inputs. A high level at the strobe terminal forces the standard output (Y) low and the inverted output (W) high.

7.2 Functional Block Diagram



Pin numbers shown are for the D, J, N, NS, PW, and W packages.

7.3 Device Functional Modes

表 7-1. Function Table⁽¹⁾

INPUTS				OUTPUTS	
SELECT			STROBE $\bar{G}$	Y	W
C	B	A			
X	X	X	H	L	H
L	L	L	L	D0	$\bar{D0}$
L	L	H	L	D1	$\bar{D1}$
L	H	L	L	D2	$\bar{D2}$
L	H	H	L	D3	$\bar{D3}$
H	L	L	L	D4	$\bar{D4}$
H	L	H	L	D5	$\bar{D5}$
H	H	L	L	D6	$\bar{D6}$
H	H	H	L	D7	$\bar{D7}$

(1) D0, D1 . . . D7 = the level of the respective D input.

8 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the *Recommended Operating Conditions*. Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. A 0.1- μ F capacitor is recommended for this device. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. The 0.1- μ F and 1- μ F capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power terminal as possible for best results.

9 Layout

9.1 Layout Guidelines

When using multiple-input and multiple-channel logic devices inputs must not ever be left floating. In many cases, functions or parts of functions of digital logic devices are unused; for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such unused input pins must not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. All unused inputs of digital logic devices must be connected to a logic high or logic low voltage, as defined by the input voltage specifications, to prevent them from floating. The logic level that must be applied to any particular unused input depends on the function of the device. Generally, the inputs are tied to GND or V_{CC} , whichever makes more sense for the logic function or is more convenient.

10 Device and Documentation Support

TI offers an extensive line of development tools. Tools and software to evaluate the performance of the device, generate code, and develop solutions are listed below.

10.1 接收文档更新通知

要接收文档更新通知，请导航至 [ti.com](https://www.ti.com) 上的器件产品文件夹。点击 [订阅更新](#) 进行注册，即可每周接收产品信息更改摘要。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

10.2 支持资源

[TI E2E™ 支持论坛](#) 是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《[使用条款](#)》。

10.3 Trademarks

TI E2E™ is a trademark of Texas Instruments.

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10.4 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

10.5 术语表

[TI 术语表](#) 本术语表列出并解释了术语、首字母缩略词和定义。

11 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
84128012A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	84128012A SNJ54HC 151FK
8412801EA	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8412801EA SNJ54HC151J
SN54HC151J	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54HC151J
SN54HC151J.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	SN54HC151J
SN74HC151D	Obsolete	Production	SOIC (D) 16	-	-	Call TI	Call TI	-40 to 85	HC151
SN74HC151DR	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	HC151
SN74HC151DR.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC151
SN74HC151DR1G4	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC151
SN74HC151DR1G4.A	Active	Production	SOIC (D) 16	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC151
SN74HC151DRG4	Active	Production	null (null)	2500 LARGE T&R	-	Call TI	Call TI	-40 to 85	
SN74HC151DT	Obsolete	Production	SOIC (D) 16	-	-	Call TI	Call TI	-40 to 85	HC151
SN74HC151N	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74HC151N
SN74HC151N.A	Active	Production	PDIP (N) 16	25 TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74HC151N
SN74HC151NSR	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC151
SN74HC151NSR.A	Active	Production	SOP (NS) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC151
SN74HC151PW	Obsolete	Production	TSSOP (PW) 16	-	-	Call TI	Call TI	-40 to 85	HC151
SN74HC151PWR	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU SN	Level-1-260C-UNLIM	-40 to 85	HC151
SN74HC151PWR.A	Active	Production	TSSOP (PW) 16	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HC151
SN74HC151PWT	Obsolete	Production	TSSOP (PW) 16	-	-	Call TI	Call TI	-40 to 85	HC151
SNJ54HC151FK	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	84128012A SNJ54HC 151FK
SNJ54HC151FK.A	Active	Production	LCCC (FK) 20	55 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	84128012A SNJ54HC 151FK
SNJ54HC151J	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8412801EA SNJ54HC151J

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SNJ54HC151J.A	Active	Production	CDIP (J) 16	25 TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	8412801EA SNJ54HC151J

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "-" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF SN54HC151, SN74HC151 :

- Catalog : [SN74HC151](#)

- Automotive : [SN74HC151-Q1](#), [SN74HC151-Q1](#)

- Military : [SN54HC151](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product
- Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC151DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC151DR1G4	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC151NSR	SOP	NS	16	2000	330.0	16.4	8.45	10.55	2.5	12.0	16.2	Q1
SN74HC151PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.3	1.6	8.0	12.0	Q1
SN74HC151PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
SN74HC151PWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC151DR	SOIC	D	16	2500	353.0	353.0	32.0
SN74HC151DR1G4	SOIC	D	16	2500	353.0	353.0	32.0
SN74HC151NSR	SOP	NS	16	2000	353.0	353.0	32.0
SN74HC151PWR	TSSOP	PW	16	2000	367.0	367.0	35.0
SN74HC151PWR	TSSOP	PW	16	2000	353.0	353.0	32.0
SN74HC151PWR	TSSOP	PW	16	2000	356.0	356.0	35.0

TUBE

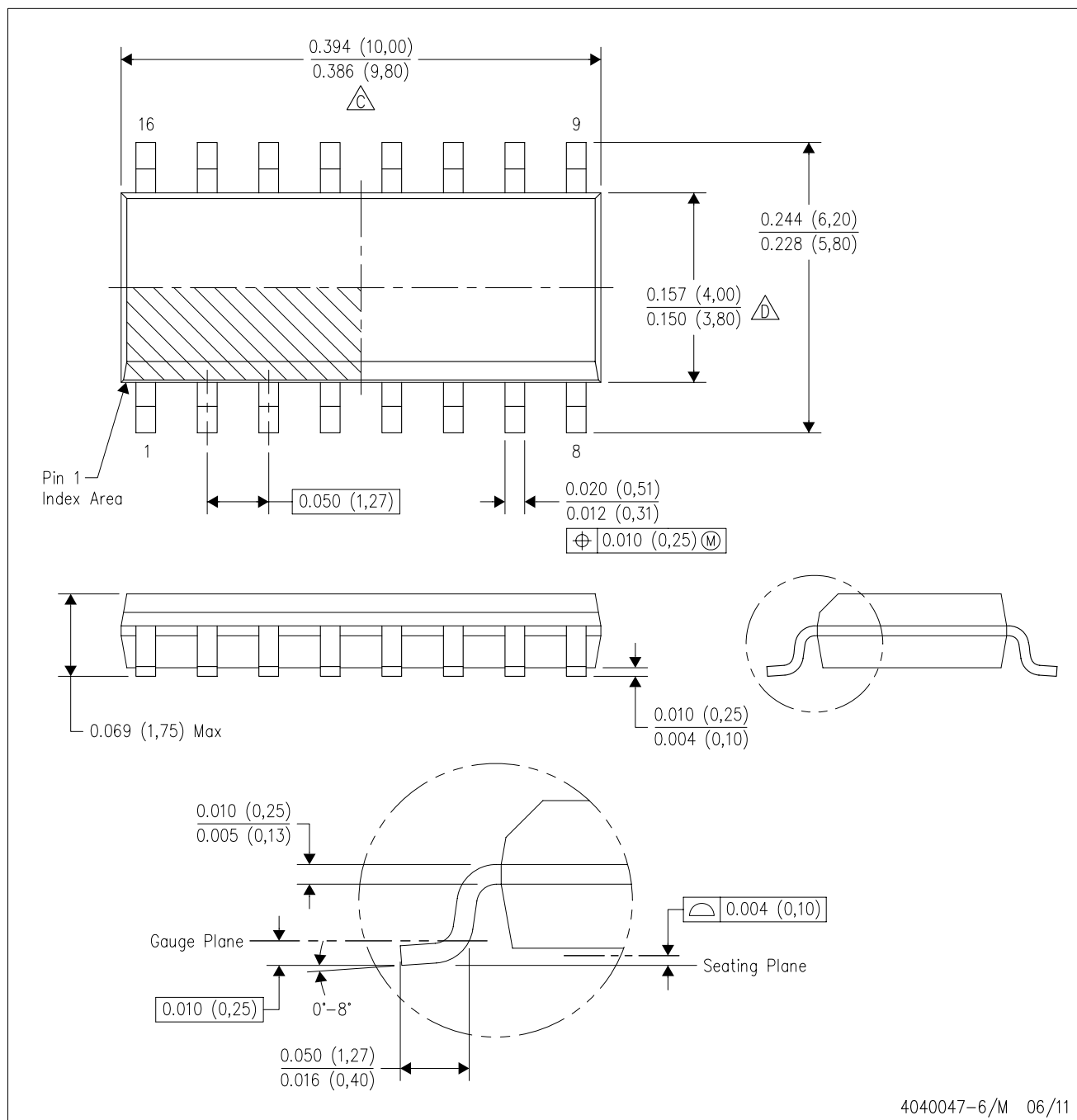


*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
84128012A	FK	LCCC	20	55	506.98	12.06	2030	NA
SN74HC151N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC151N	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC151N.A	N	PDIP	16	25	506	13.97	11230	4.32
SN74HC151N.A	N	PDIP	16	25	506	13.97	11230	4.32
SNJ54HC151FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54HC151FK.A	FK	LCCC	20	55	506.98	12.06	2030	NA

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AC.

GENERIC PACKAGE VIEW

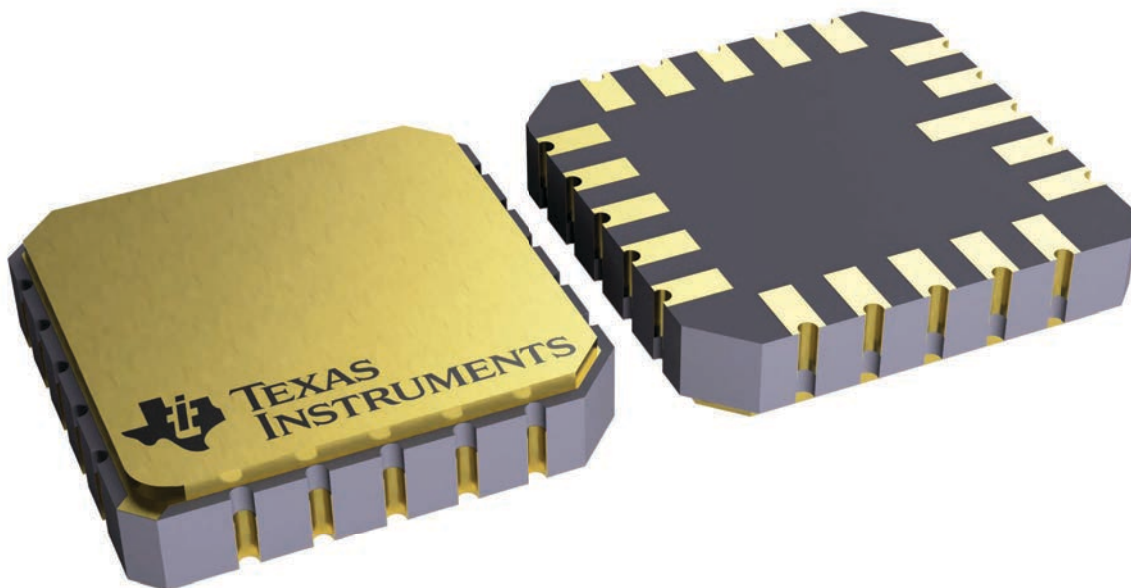
FK 20

LCCC - 2.03 mm max height

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.

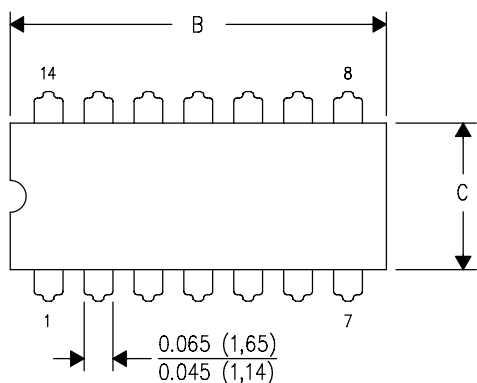


4229370VA\

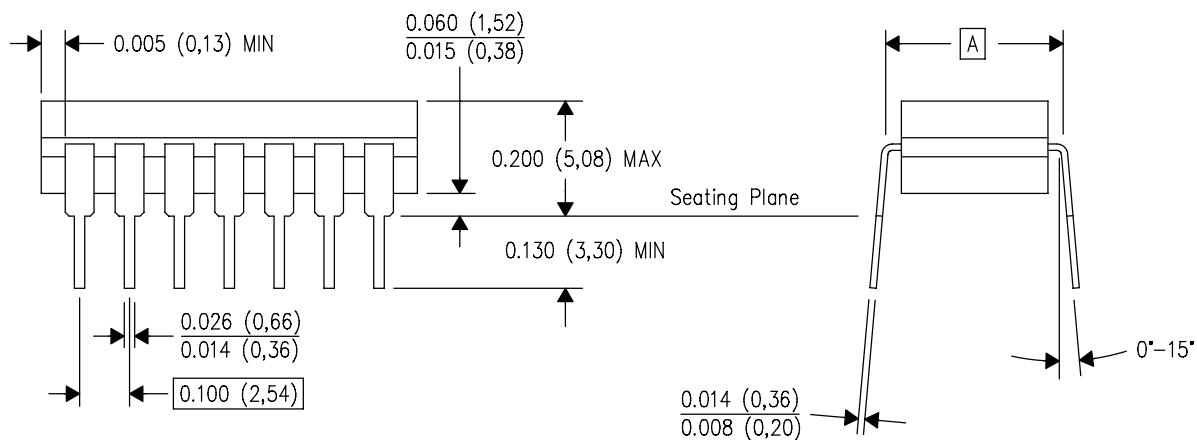
J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE

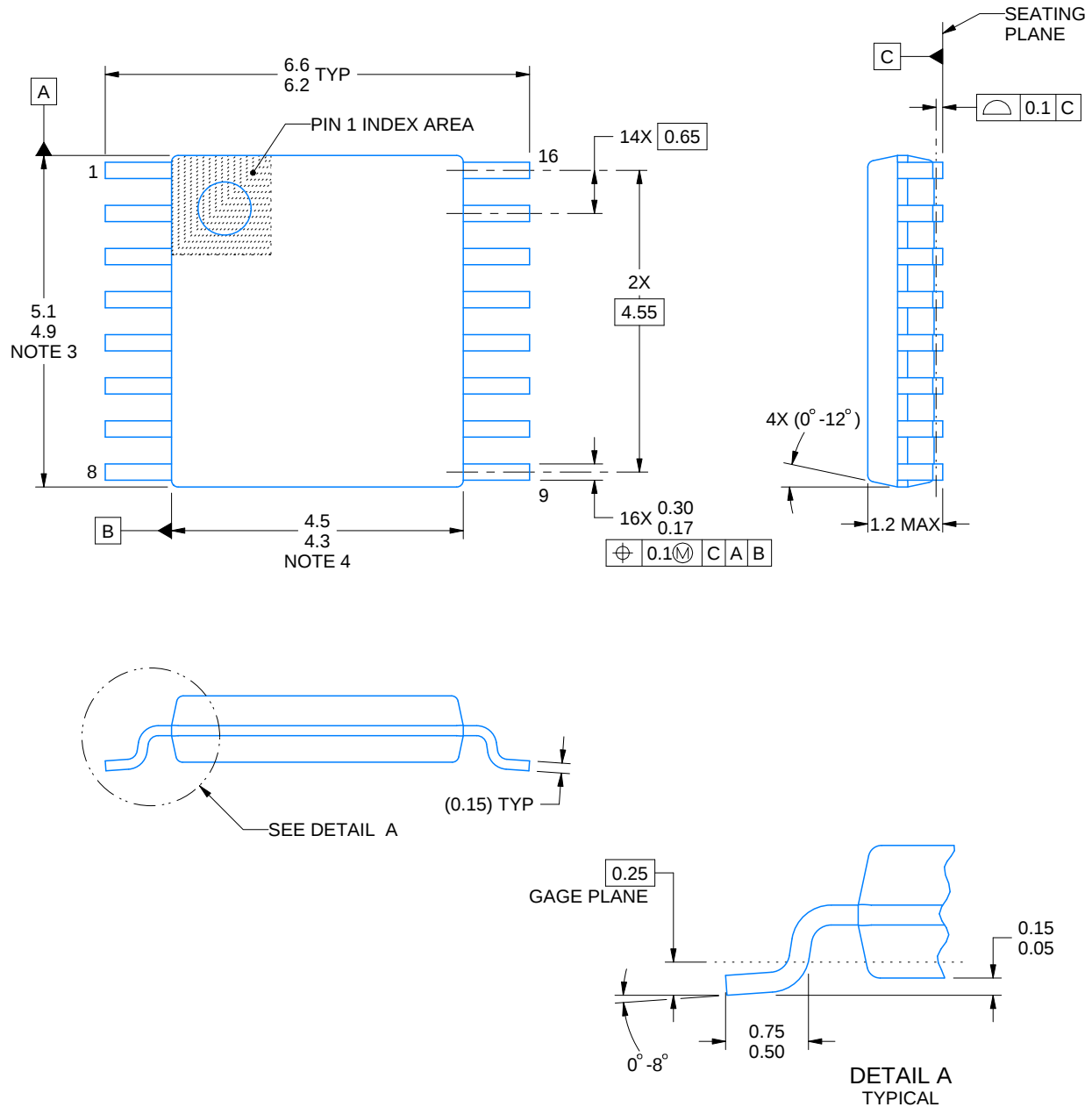
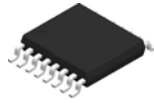


PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package is hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.



4220204/B 12/2023

NOTES:

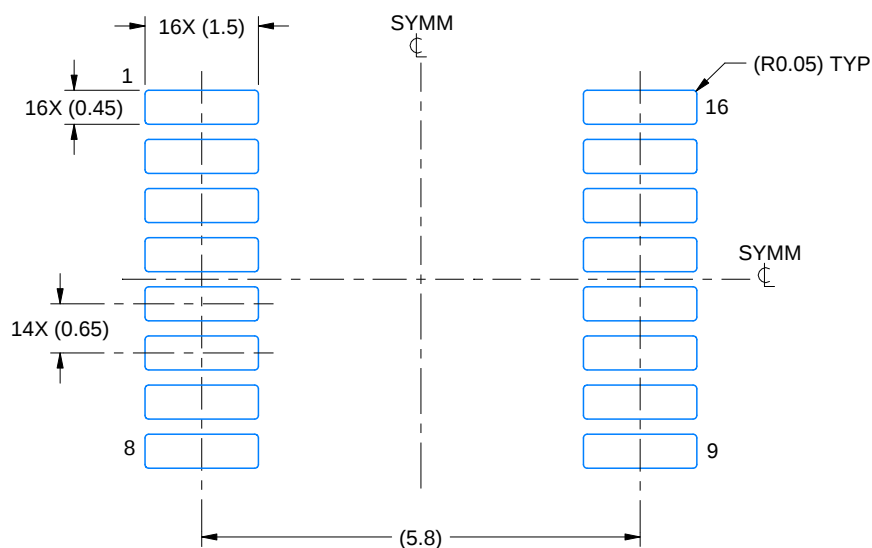
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

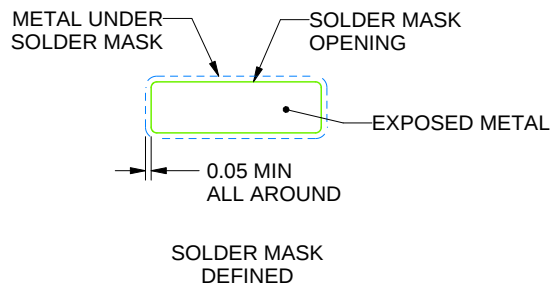
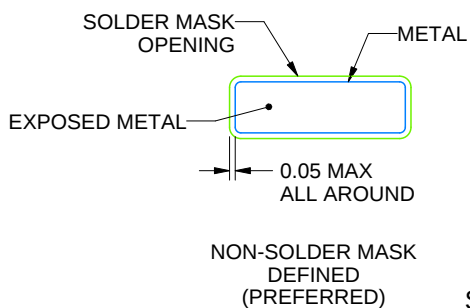
PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



SOLDER MASK DETAILS

4220204/B 12/2023

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

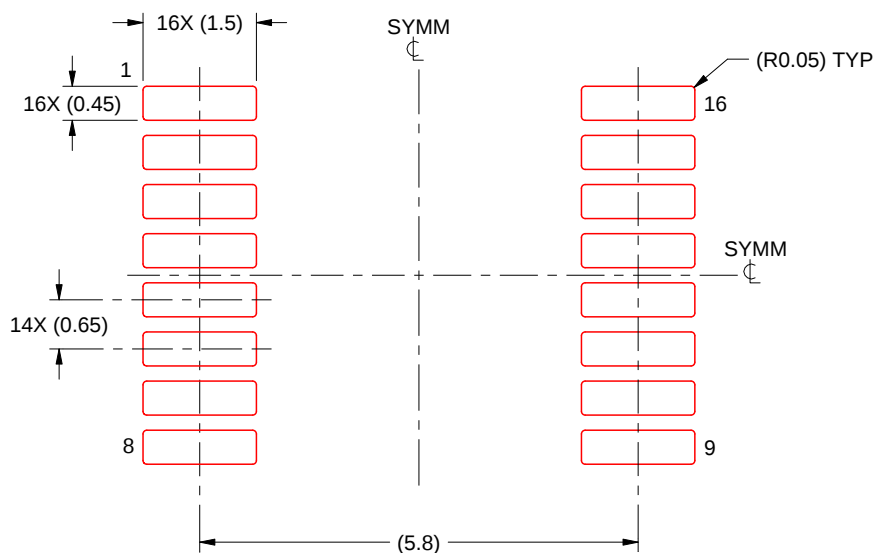
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220204/B 12/2023

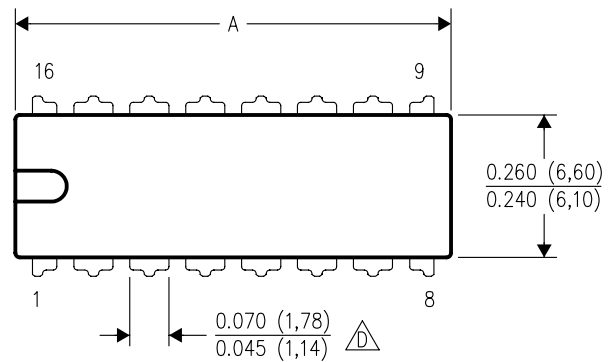
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

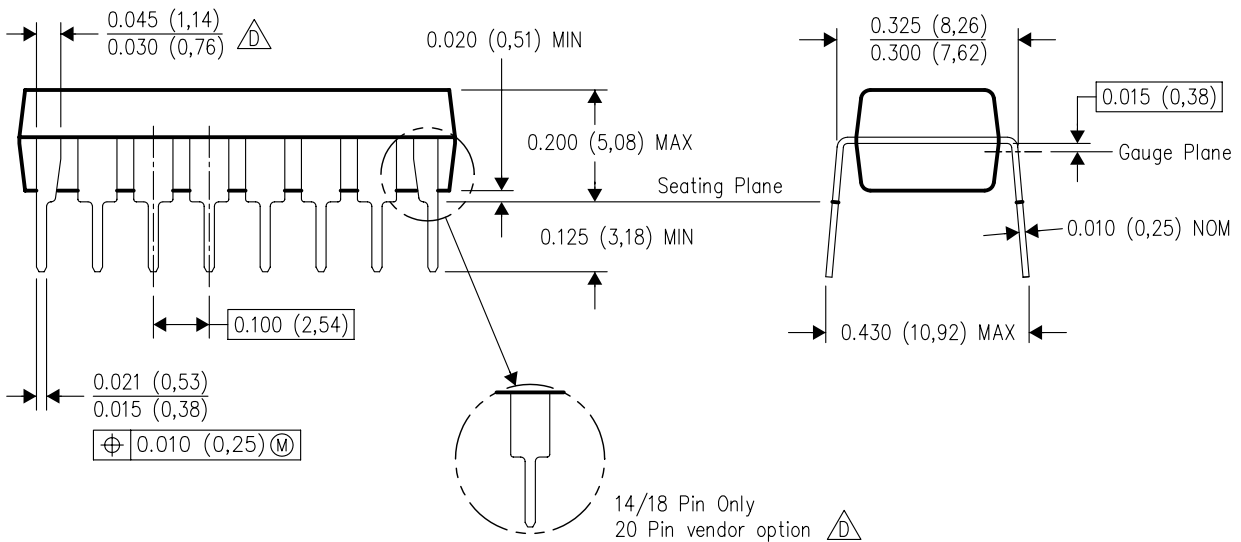
N (R-PDIP-T**)

16 PINS SHOWN

PLASTIC DUAL-IN-LINE PACKAGE



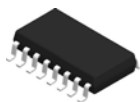
PINS **	14	16	18	20
DIM				
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



14/18 Pin Only
20 Pin vendor option

4040049/E 12/2002

- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

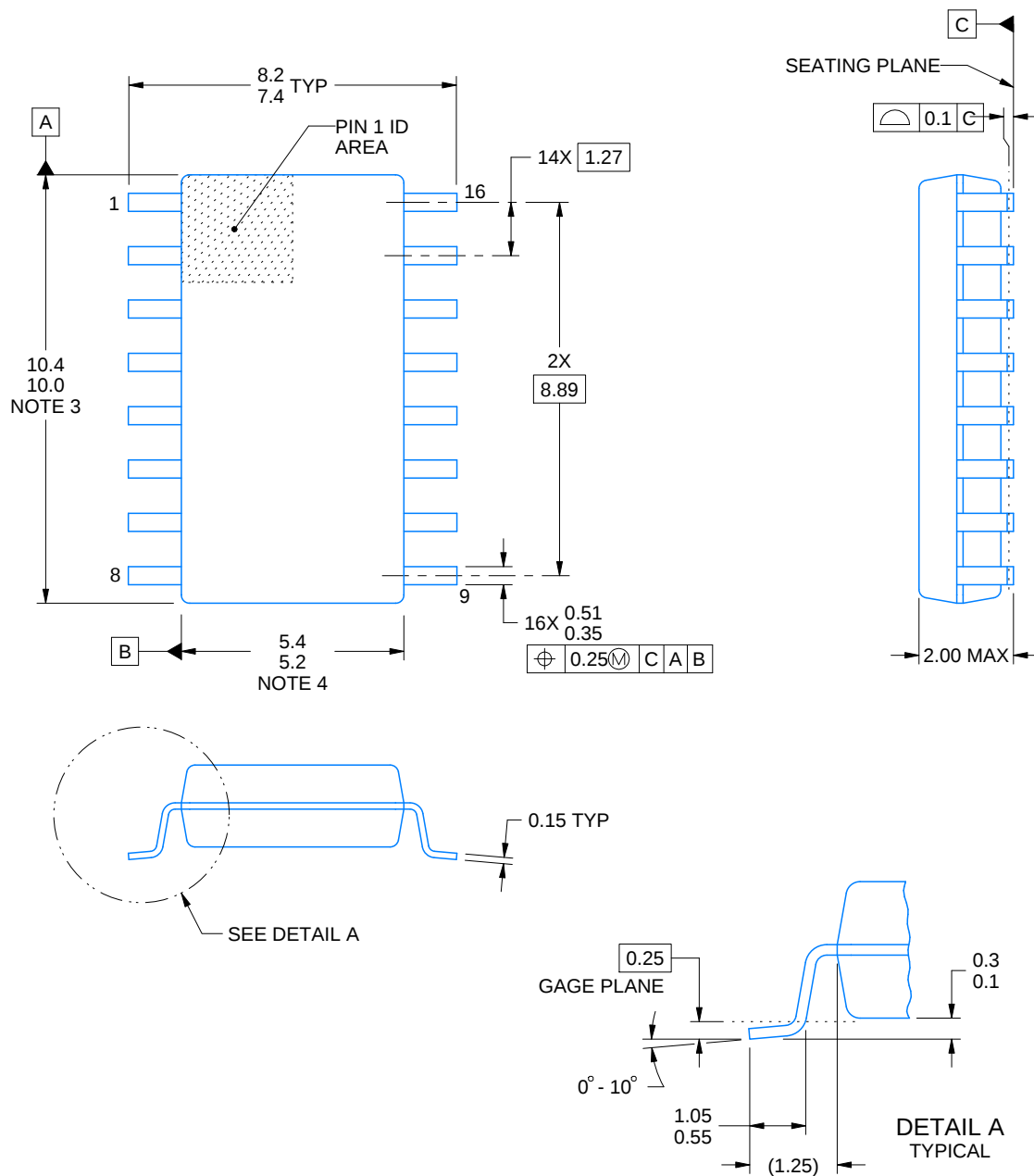


PACKAGE OUTLINE

NS0016A

SOP - 2.00 mm max height

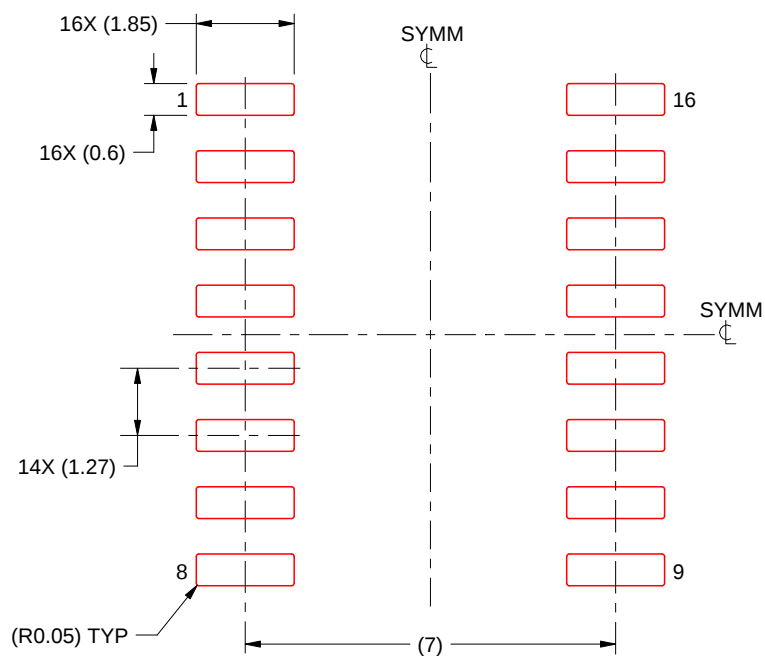
SOP



4220735/A 12/2021

NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.



SOLDER PASTE EXAMPLE
 BASED ON 0.125 mm THICK STENCIL
 SCALE:7X

4220735/A 12/2021

NOTES: (continued)

7. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
8. Board assembly site may have different recommendations for stencil design.

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